

# **SMB1N-720D**

- Infrared High Power LED
- 720 nm, 520 mW
- InGaAInP chip, 1000 x 1000 μm
- PA9T SMD package
- Beam Angle: ± 64°



### Description



**SMB1N-720D** is a surface mount InGaInP based high power infrared LED, with a typical peak wavelength of 720 nm and optical output power of 520 mW @ 600 mA. It comes in polyamide resin SMD package (PA9T) with silver plated soldering pads (lead free solderable), copper heat sink, and silicone resin mold. Additional variants with different beam angles are available on request.

## Maximum Ratings\*

Parameter	Cumbal	Va	Heit	
Parameter	Symbol	Min.	Max.	Unit
Power Dissipation	PD		2000	mW
Forward Current	lF		800	mA
Pulse Forward Current **	<b>I</b> FP		2000	mA
Reverse Voltage	<b>U</b> R		5	V
Reverse Current (U <sub>R</sub> = 5V)	$I_R$		10	μΑ
Thermal Resistance	RTHJA		10	K/W
Junction Temperature	$T_J$		120	°C
Operating Temperature	TCASE	- 40	+ 100	°C
Storage Temperature	T <sub>STG</sub>	- 40	+ 100	°C
Lead Solder Temperature (t <sub>max</sub> . 5s)	T <sub>SLD</sub>		+ 250	°C

<sup>\*</sup>Operating close to or exceeding these parameters may damage the device

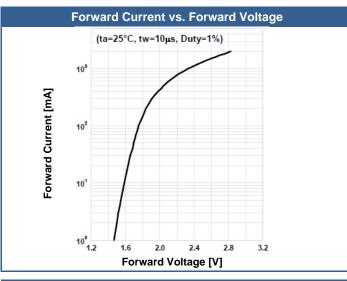
### Electro-Optical Characteristics (TCASE = 25°C)

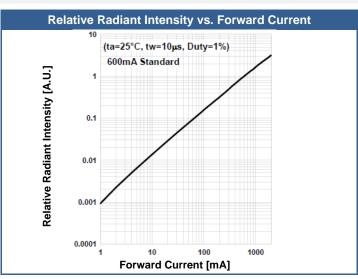
Parameter	Symbol	Conditions	Min.	Values Typ.	Max.	Unit
Peak Wavelength	λp	IF=600 mA	710		730	nm
Half Width	$\lambda_{\Delta}$	IF=600 mA		18		nm
Forward Voltage	$U_F$	IF=600 mA		2.1	2.4	V
	$U_{FP}$	I <sub>FP</sub> =2 A*		2.8		
Total Radiated Power	Po	IF=600 mA	360	520		mW
		I <sub>FP</sub> =2 A*		1600		
Radiant Intensity	lE	IF=600 mA		170		mW/sr
		I <sub>FP</sub> =2 A*		530		
Beam Angle	2θ <sub>1/2</sub>	$I_F=100 \text{ mA}$		128		deg.
Rise Time	t <sub>r</sub>	IF=600 mA		100		ns
Fall Time	$t_f$	IF=600 mA		100		ns

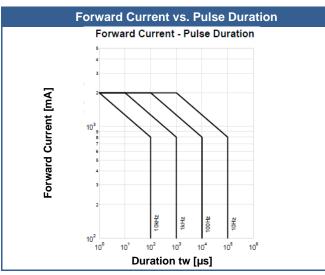
<sup>\*</sup> duty cycle = 1 %, pulse width = 10 µs

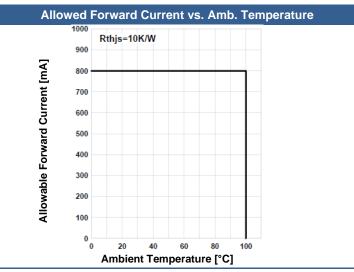
<sup>\*\*</sup> duty cycle = 1 %, pulse width = 10  $\mu$ s

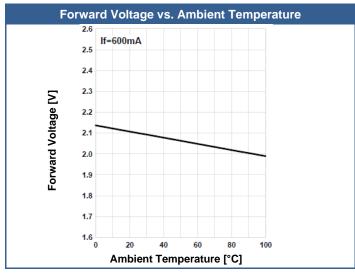
# **Typical Performance Curves**

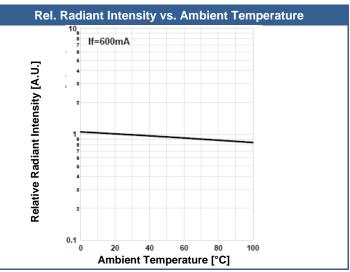




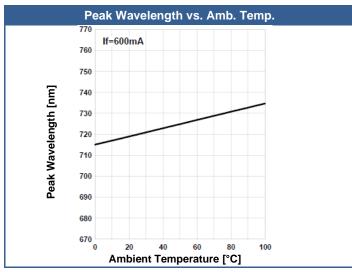


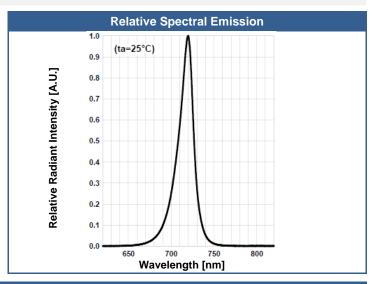


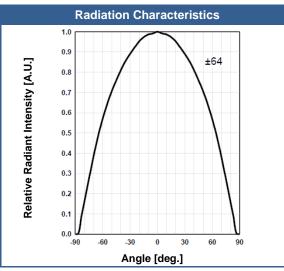


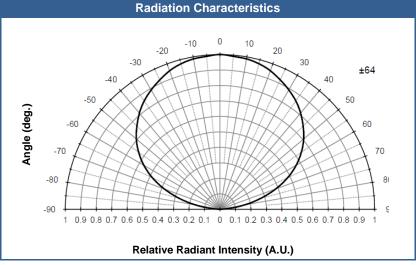


# **Typical Performance Curves**

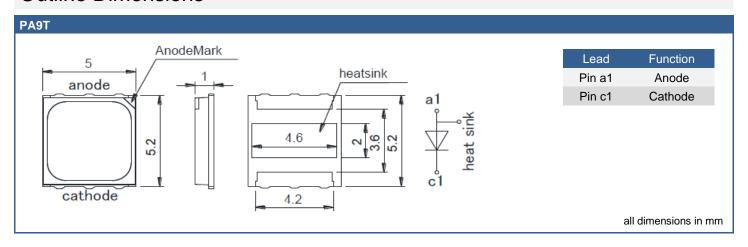








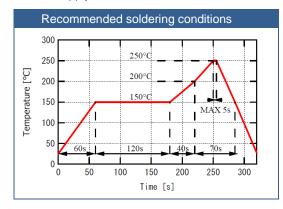
### **Outline Dimensions**

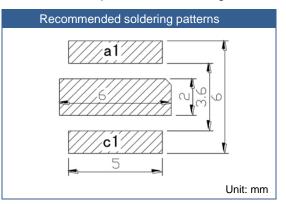


### **General Notes**

#### Soldering

- · Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- Do not apply current to the LED until it has cooled down to room temperature after soldering





#### Cleaning

- . Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended
- DO NOT USE acetone, chloroseen, trichloroethylene, or MKS
- DO NOT USE ultrasonic cleaners

#### Static Electricity

- LEDs are sensitive to electrostatic discharge (ESD).
- Precautions against ESD must be taken when handling or operating these LEDs
- Surge voltage or electrostatic discharge can result in complete failure of the LED.

#### Radiation

- During operation these LEDs do emit light, which could be hazardous to skin and eyes, and may cause cancer.
- · Do avoid exposure to the emitted light. Protective glasses if needed
- It is further advised to attach a warning label on products/systems.

#### Operation

- · Do only operate LEDs with a current source.
- Running these LEDs from a voltage source will result in complete failure of the device.
- Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.

#### Storage

- The maximum shelf life of LEDs in the originally sealed aluminum bag is 12 months.
- Before opening the aluminum bag, please store it at <30 °C, <60 % RH.
- After opening the aluminum bag, please solder the LEDs within 72 hours (floor life) at 5 − 30 °C, <50 % RH.</li>
- Put any unused, remaining LEDs and silica gel back in the same aluminum bag and then vacuum-seal the bag.
- It is recommended to keep the re-sealed bag in a desiccator at <30%RH.</li>

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